

Lattice Semiconductor Corporation - LFEC1E-5T100C Datasheet





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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	1500
Total RAM Bits	18432
Number of I/O	67
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec1e-5t100c

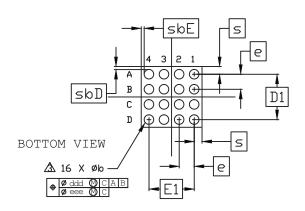
Email: info@E-XFL.COM

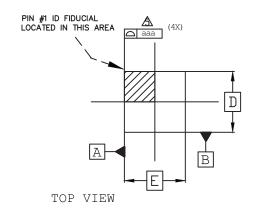
Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

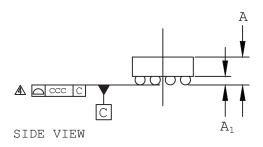


16-Ball WLCS Package Option 2: iCE40 UltraLite™

Dimensions in Millimeters







NOTES:

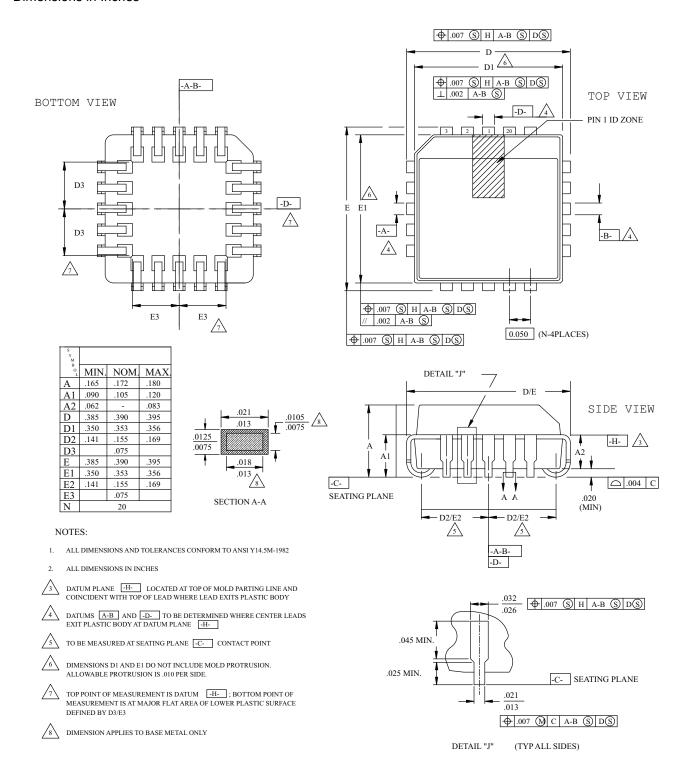
- 1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- \triangle PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
- $\underline{\mathbb{A}}$ BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

REF.	Min.	Nom.	Max.		
Α	0.413	0.452	0.491		
A1	0.122	0.152	0.182		
b	0.188	0.218	0.248		
D	1.	409 BS	C		
Ε	1.	409 BS	С		
D1	1.05 BSC				
E1	1.05 BSC				
е	0.35 BSC				
S	-	0.180	-		
sbD	0.067	0.071	0.072		
sbE	0.067 0.071 0.072				
ممم	0.03				
CCC	0.03				
ddd	0.050				
eee		0.015			



20-Pin PLCC Package

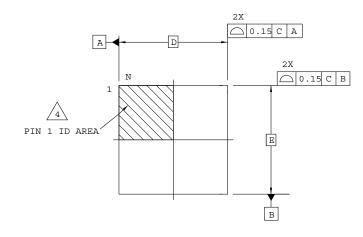
Dimensions in Inches

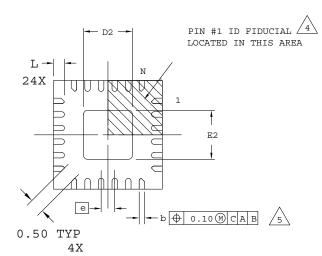




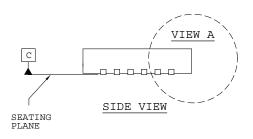
24-Pin QFNS Package

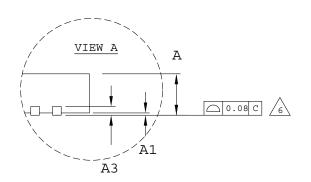
Dimensions in Millimeters





TOP VIEW





BOTTOM VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- 3. DRAWING CONFORMS TO JEDEC MO-220, VARIATION VGGD-9.

 $\sqrt{4}$

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

5

DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

6

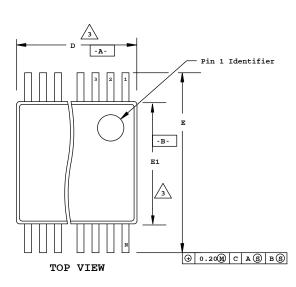
APPLIES TO EXPOSED PORTION OF TERMINALS.

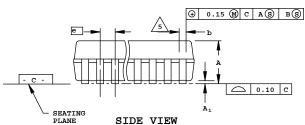
SYMBOL	MIN.	NOM.	MAX.	
A	0.80	0.90	1.00	
A1	0.00	0.02	0.05	
A3		0.2 REF		
D	4.0 BSC			
D2	1.05	-	2.45	
E	4.0 BSC			
E2	1.05	-	2.45	
b	0.18	0.25	0.30	
е	0.50 BSC			
L	0.45	0.50	0.55	

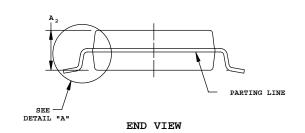


28-Pin SSOP Package

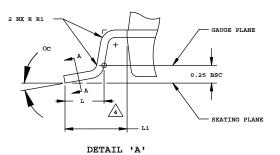
Dimensions in Millimeters

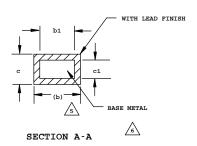






S Y	COMMON						
M B	DIMENSIONS						
O L	MIN.	NOM.	MAX.				
Α			2.0				
A	0.05						
A ₂	1.65	1.75	1.85				
b	0.22	-	0.38				
b ₁	0.22	0.30	0.33				
С	0.09		0.25				
Cı	0.09	0.15	0.21				
D	9.90	10.20	10.50				
E1	5.00	5.30	5.60				
е		0.65 BSC					
Е	7.40	7.80	8.20				
L	0.55	0.75	0.95				
L1	1.25 REF.						
N		28					
oc	0	4	8				
R1	0.09						





NOTES:

- 1. CONTROLLING DIMENSION: MILLIMETERS.
- 2. DIMENSIONING & TOLERANCES PER ANSI.Y14.5M-1982.

"D" & "E1" DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, BUT DO INCLUDE MOLD MISMATCH AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.20mm PER SIDE.

4. TO BE DETERMINED AT THE SEATING PLANE

DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION/INTRUSION.
ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13mm TOTAL IN
EXCESS OF b DIMENSION AT MAXIMUM MATERIAL CONDITION.
DAMBAR INTRUSION SHALL NOT REDUCE DIMENSION b BY MORE
THAN 0.07mm AT LEAST MATERIAL CONDITION.

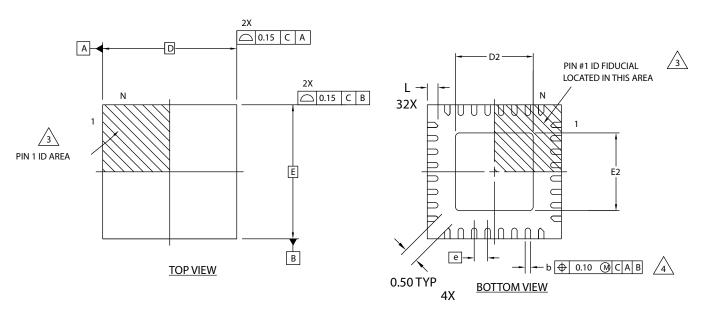
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 & 0.25mm FROM THE LEAD TIP

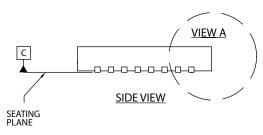
7. "N" IS THE NUMBER OF TERMINAL POSITIONS

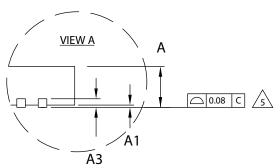


32-Pin QFN Package Option 1: Power Manager II, iCE40™

Dimensions in Millimeters







NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

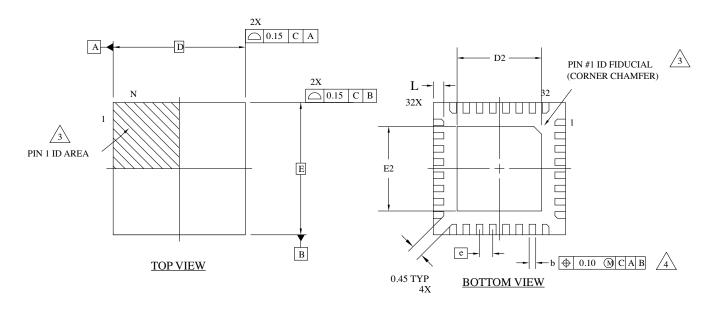
DIMENSION b APPLIES TO PLATED
TERMINAL AND IS MEASURED BETWEEN
0.15 AND 0.30 mm FROM TERMINAL TIP.

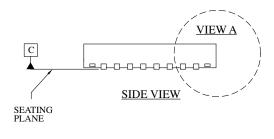
SYMBOL	MIN.	NOM.	MAX.
А	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3		0.2 REF	
D	5.0 BSC		
D2	1.25	2.70	3.75
E	5.0 BSC		
E2	1.25	2.70	3.75
b	0.18	0.24	0.30
е	0.50 BSC		
L	0.30	0.40	0.50

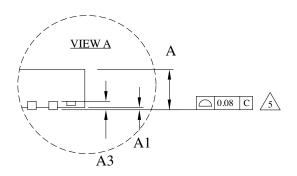


32-Pin QFN Package Option 2: MachXO2™

Dimensions in Millimeters







NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

DIMENSION 6 APPLIES TO PLATED
TERMINAL AND IS MEASURED BETWEEN
0.15 AND 0.30 mm FROM TERMINAL TIP.

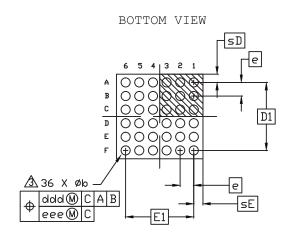
APPLIES TO EXPOSED PORTION OF TERMINALS.

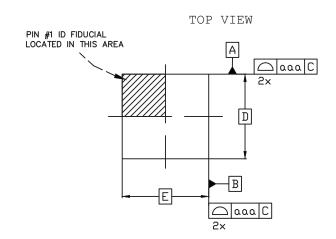
SYMBOL MIN. NOM. MAX. A 0.50 0.55 0.60 A1 0.00 0.02 0.05 A3 0.2 REF D 5.0 BSC D2 3.10 3.20 3.30 E 5.0 BSC E2 3.10 3.20 3.30 b 0.20 0.25 0.30 e 0.50 BSC L 0.35 0.40 0.45					
A1 0.00 0.02 0.05 A3 0.2 REF D 5.0 BSC D2 3.10 3.20 3.30 E 5.0 BSC E2 3.10 3.20 3.30 b 0.20 0.25 0.30 e 0.50 BSC	SYMBOL	MIN.	NOM.	MAX.	
A3 0.2 REF D 5.0 BSC D2 3.10 3.20 3.30 E 5.0 BSC E2 3.10 3.20 3.30 b 0.20 0.25 0.30 e 0.50 BSC	A	0.50	0.55	0.60	
D 5.0 BSC D2 3.10 3.20 3.30 E 5.0 BSC E2 3.10 3.20 3.30 b 0.20 0.25 0.30 e 0.50 BSC	A1	0.00	0.02	0.05	
D2 3.10 3.20 3.30 E 5.0 BSC E2 3.10 3.20 3.30 b 0.20 0.25 0.30 e 0.50 BSC	A3	0.2 REF			
E 5.0 BSC E2 3.10 3.20 3.30 b 0.20 0.25 0.30 e 0.50 BSC	D	5.0 BSC			
E2 3.10 3.20 3.30 b 0.20 0.25 0.30 e 0.50 BSC	D2	3.10	3.20	3.30	
b 0.20 0.25 0.30 e 0.50 BSC	Е	5.0 BSC			
e 0.50 BSC	E2	3.10	3.20	3.30	
	b	0.20	0.25	0.30	
L 0.35 0.40 0.45	e	0.50 BSC			
	L	0.35	0.40	0.45	

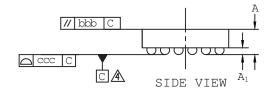


36-Ball WLCS Package Option 2: MachXO3[™]

Dimensions in Millimeters







NOTES:

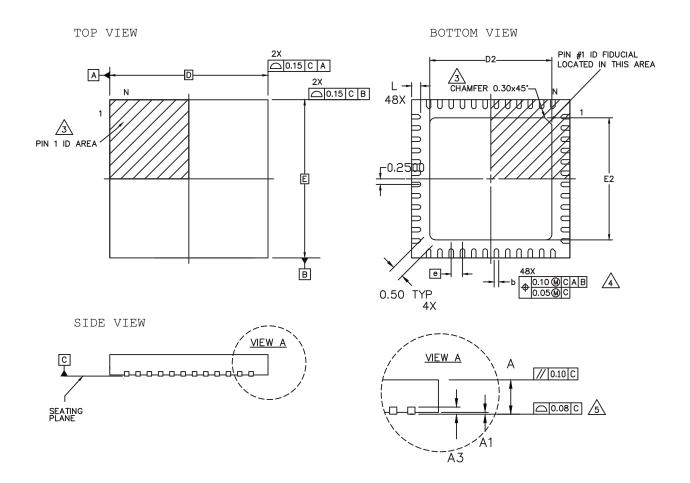
- 1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM [C].
- \triangle PRIMARY DATUM $\boxed{\text{C}}$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

REF.	Min.	Nom.	Max.
A	0.510	0.543	0.576
A1	0.167	0.196	0.225
b	0.239	0.266	0.319
D		2.487 BS	C
E		2.541 BS	C
D1		2.00 BSC	;
E1	2.00 BSC		
е		0.40 BSC	:
sD	ı	0.244	1
sE	ı	0.271	-
aaa	0.025		
bbb	0.060		
ccc	0.030		
ddd	0.0150		
eee		0.050	



48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra, iCE40 UltraPlus, MachXO2

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

<u>3</u>

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

4

DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

/5\

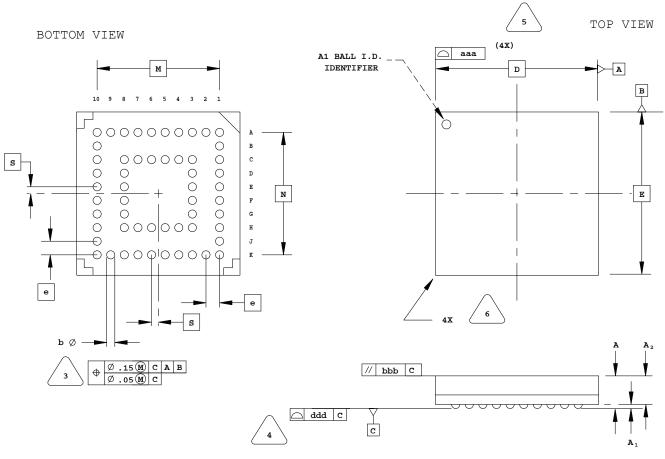
APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
А	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3		0.2 REF	
D	7.0 BSC		
D2	5.30	5.40	5.50
E	7.0 BSC		
E2	5.30	5.40	5.50
b	0.15	0.20	0.25
е	0.50 BSC		
L	0.35	0.40	0.45



56-Ball csBGA Package

Dimensions in Millimeters



SIDE VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\[\]$



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

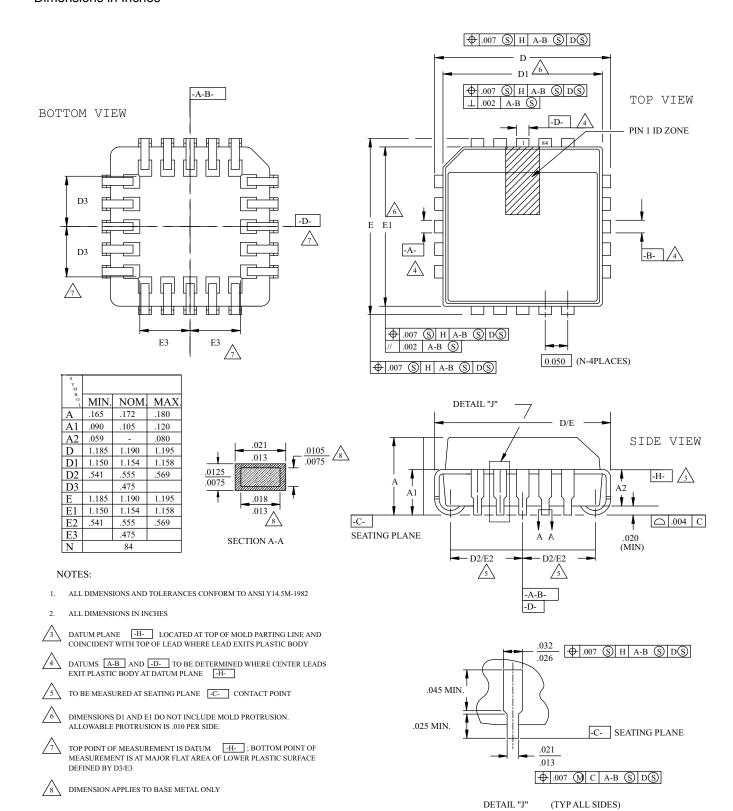


SYMBOL	MIN.	NOM.	MAX.
A	1.10	1.23	1.35
A1	0.15	-	-
A2	-	-	1.10
D/E	6	.00 BSC	
M/N	4	.50 BSC	
s	0	25 BSC	
b	0.25	0.30	0.35
е	0	.50 BSC	
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08



84-Pin PLCC Package

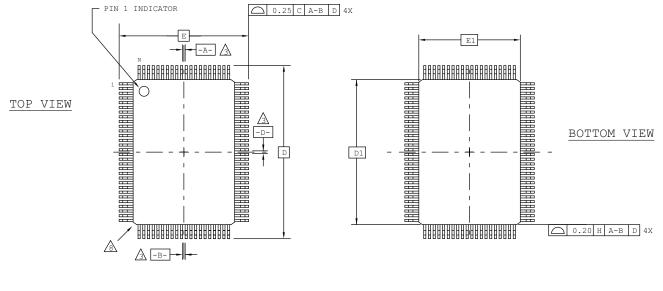
Dimensions in Inches

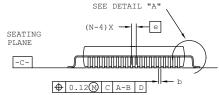


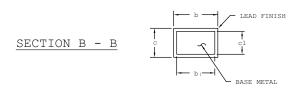


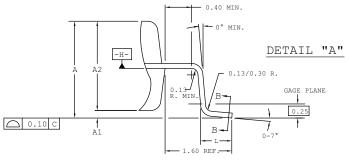
100-Pin PQFP Package

Dimensions in Millimeters









NOTES:

- 1.0 DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2.0 ALL DIMENSIONS ARE IN MILLIMETERS.
- DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- 4.0 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION.
 ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1
 DIMENSIONS.
- 5.0 THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 7.0 A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

8	EXACT	SHAPE	OF	EACH	CORNER	IS	OPTIONAL.

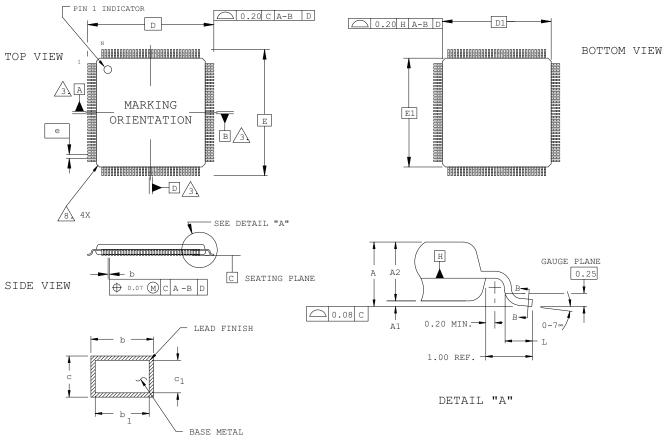
♠ EXACT SHAPE OF EXPOSED HEATSINK IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.	
A	-	-	3.40	
A1	0.25	1	0.50	
A2	2.50	2.70	2.90	
D		23.20 BSC	!	
D1		20.00 BSC	!	
E		17.20 BSC	!	
E1		14.00 BSC	!	
L	0.73 0.88 1.03			
N	100			
е	0.65 BSC			
b	0.22	1	0.40	
b1	0.22	0.30	0.36	
U	0.11	-	0.23	
c1	0.11	0.15	0.19	



128-Pin TQFP Package

Dimensions in Millimeters



SECTION B - B

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

3 DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B: THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

/8\ EXACT SHAPE OF EACH CORNER IS OPTIONAL.

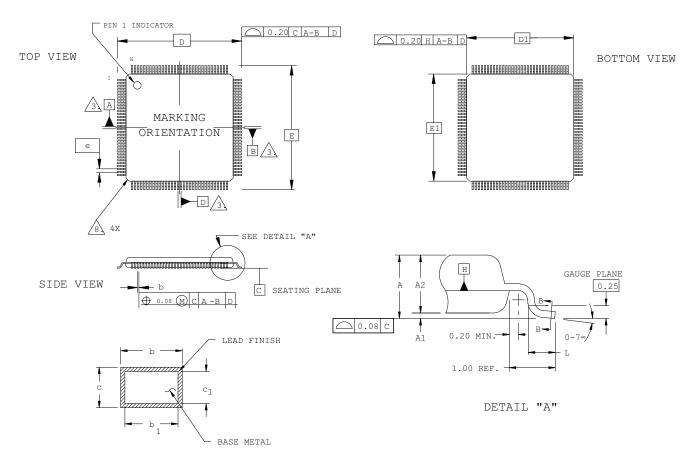
SIDE VIEW

SYMBOL	MIN.	NOM.	MAX.	
A	-	-	1.60	
A1	0.05	-	0.15	
A2	1.35	1.40	1.45	
D		16.00 BSC		
D1		14.00 BSC		
Е	16.00 BSC			
E1		14.00 BSC		
L	0.45 0.60 0.75			
N	128			
е		0.40 BSC		
b	0.13	0.18	0.23	
b1	0.13	0.16	0.19	
С	0.09	0.15	0.20	
c1	0.09	0.13	0.16	



144-Pin TQFP Package

Dimensions in Millimeters



SECTION B - B

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\sqrt{}_3$ DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B: $\begin{tabular}{lllll} THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP. \\ \end{tabular}$
- 7. Al is defined as the distance from the seating plane to the lowest point on the package body.

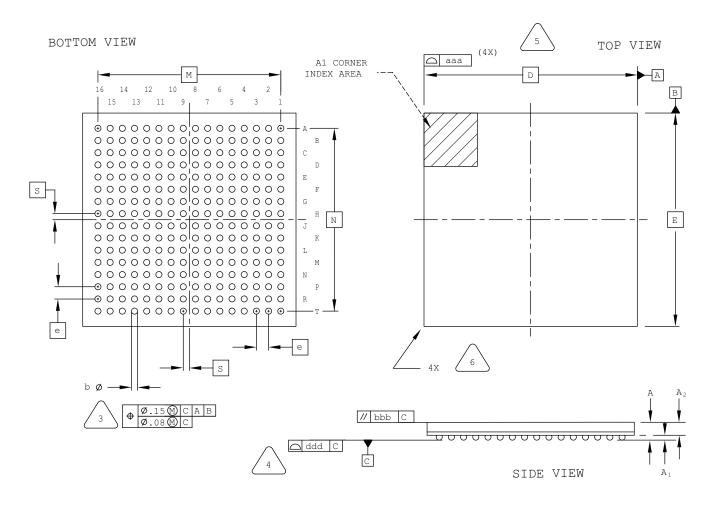
 $\sqrt{8}$ EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D		22.00 BSC	
D1		20.00 BSC	
Е	22.00 BSC		
E1	20.00 BSC		
L	0.45	0.60	0.75
N	144		
е	0.50 BSC		
b	0.17 0.22 0.2		0.27
b1	0.17	0.20	0.23
С	0.09	0.15	0.20
c1	0.09	0.13	0.16



256-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

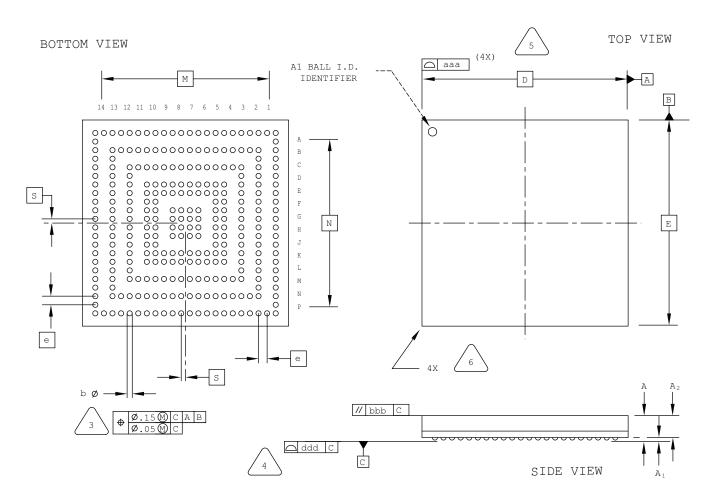
7. REFERENCE JEDEC MO-275, VARIATION JJAB-2.

SYMBOL	MIN.	NOM.	MAX.
А	_	-	1.70
A1	0.25	_	_
A2	0.65	_	-
D/E	14.0 BSC		
M/N	12.0 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
е	0.80 BSC		
aaa	_	_	0.15
bbb	_	_	0.20
ddd	_	_	0.20



284-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

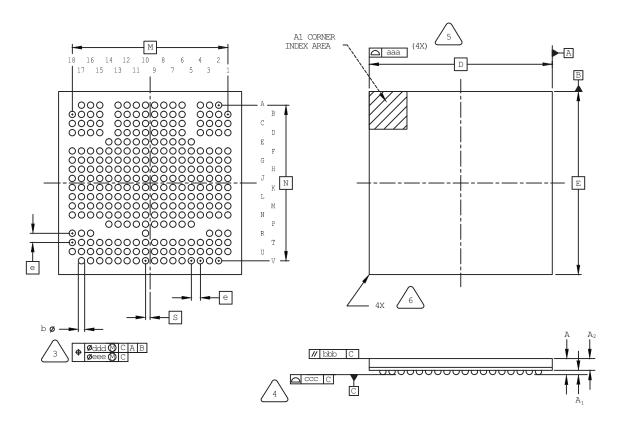


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.00
A1	0.15	_	ı
A2	_	-	0.85
D/E	12.00 BSC		
M/N	10.50 BSC		
S	0.25 BSC		
b	0.25	0.31	0.37
е	0.50 BSC		
aaa	-	_	0.10
bbb	_	_	0.10
ddd	_	_	0.08



285-Ball csfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

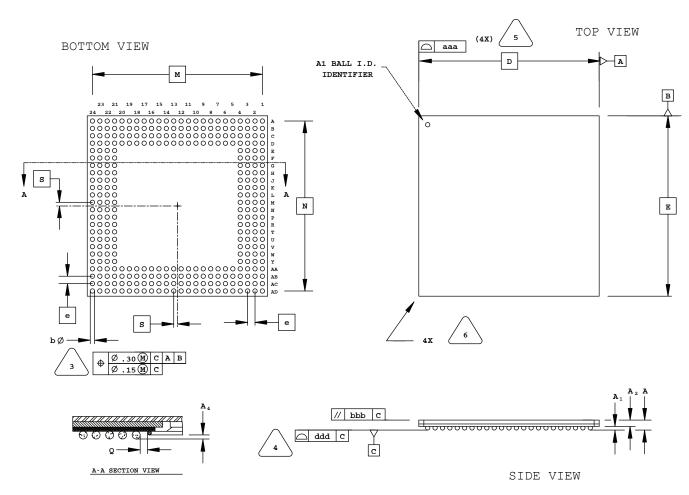


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.30
A1	0.15	_	_
A2	-	-	1.00
D/E	1	0.00 BSC	
M/N	8.50 BSC		
S	0.25 BSC		
b	0.25 0.30		0.35
е	0.50 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.05		



320-Ball SBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES
 PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

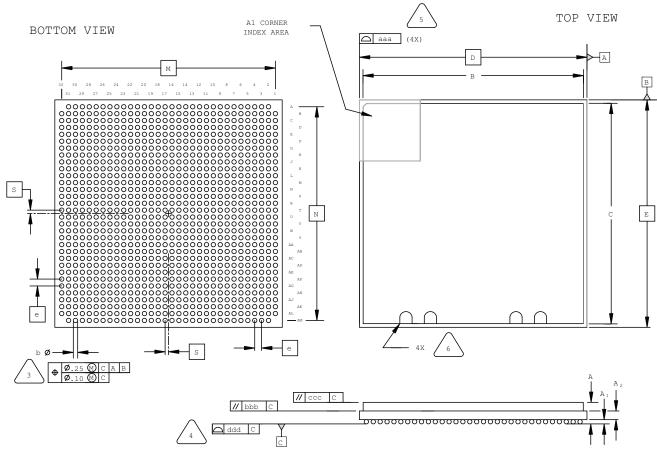


SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.50	0.65	0.80
A2	0.80	0.90	1.00
D/E	3:	1.00 BSC	
M/N	29.21 BSC		
s	0.635 BSC		
b	0.60	0.75	0.90
е	1.27 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20



1020-Ball Organic fcBGA Package

Dimensions in Millimeters



SIDE VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

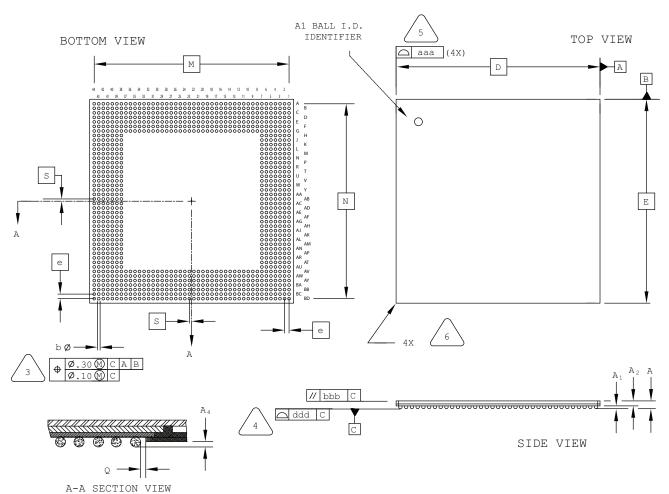


SYMBOL	MIN.	NOM.	MAX.
А	2.52	3.12	3.82
A1	0.30	0.50	0.70
A2	1	.24 REF	
B/C	31.10	32.00	32.90
D/E	33.00 BSC		
M/N	31.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa			0.20
bbb	c		0.25
ccc	-	=	0.35
ddd	-	=	0.20



1036-Ball ftSBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

3

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

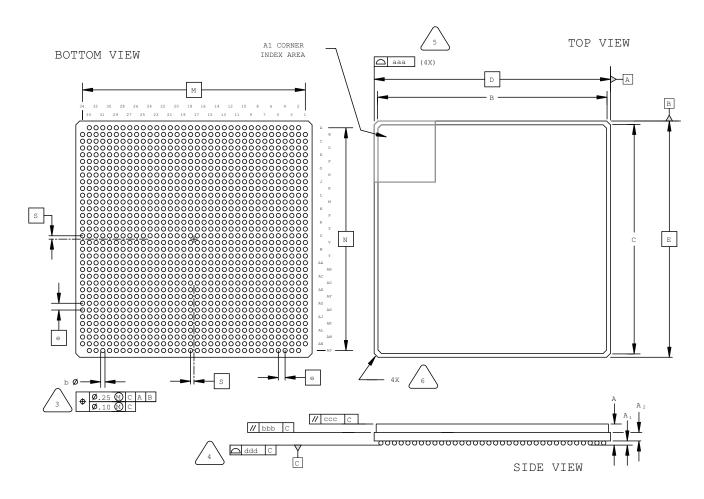


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.80
A1	0.40	0.55	0.70
A2	0.90	0.98	1.10
D/E	4.	5.00 BSC	
M/N	43.00 BSC		
S	0.50 BSC		
b	0.50	0.65	0.80
е	1.00 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.35
ddd	-	-	0.20



1152-Ball Ceramic fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

 DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

3

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C





BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.
А	4.00	4.60	5.20
A1	0.30	0.50	0.70
A2	1	.40 REF	
B/C	33.10	34.00	34.90
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	0.:		0.25
ccc	-	-	0.35
ddd	_	_	0.20